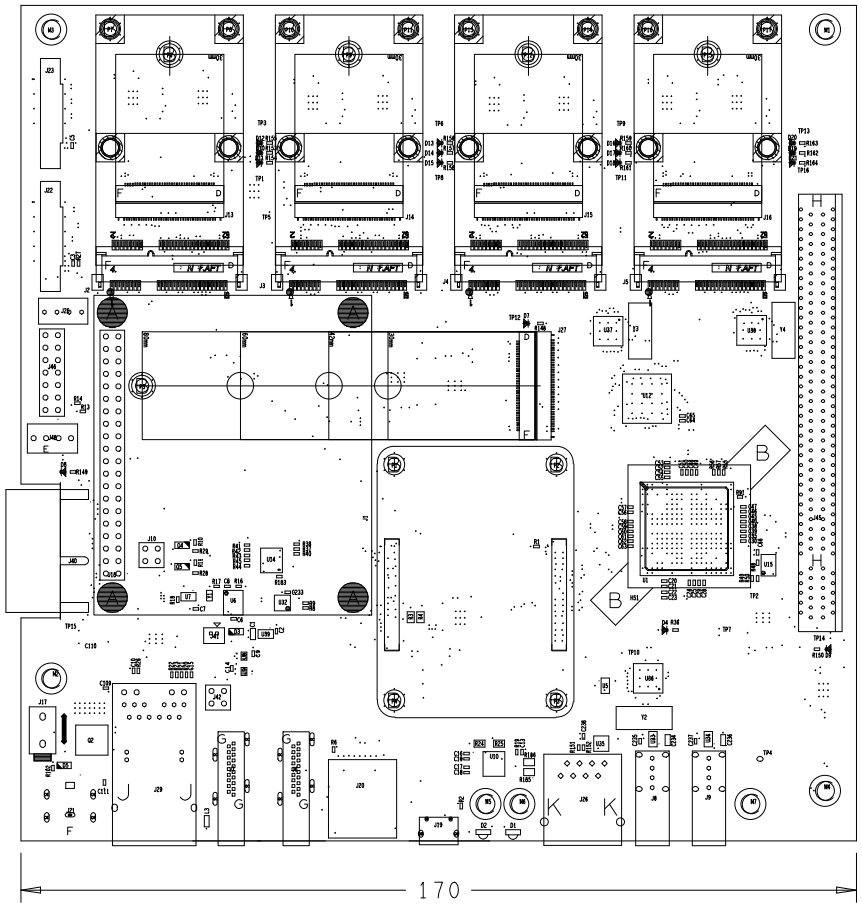

DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILLIMETERS					
FIGURE	FINISHED_SIZE	TOOL_SIZE	ROTATION	PLATED	QTY
·	0.2	-	-	PLATED	1551
▫	0.55	-	-	PLATED	40
◦	0.7	-	-	PLATED	164
◦	0.9	-	-	PLATED	28
○	1.0	-	-	PLATED	70
◇	1.15	-	-	PLATED	10
○	1.35	-	-	PLATED	9
○	1.56	-	-	PLATED	4
□	1.7	-	-	PLATED	1
○	1.8	-	-	PLATED	2
A	2.75	-	-	PLATED	4
B	3.0	-	-	PLATED	19
C	3.96	-	-	PLATED	7
D	1.1	-	-	NON-PLATED	9
E	1.25	-	-	NON-PLATED	1
F	1.6	-	-	NON-PLATED	10
G	1.8	-	-	NON-PLATED	4
H	2.35	-	-	NON-PLATED	2
I	2.5	-	-	NON-PLATED	4
J	3.25	-	-	NON-PLATED	2
K	3.4	-	-	NON-PLATED	2
▪	0.85x0.65	-	90.000	PLATED	2
⊕	1.5x1.0	-	90.000	PLATED	2
⊕	2.0x1.0	-	90.000	PLATED	4
⊕	2.1x0.8	-	0.000	PLATED	1
⊕	2.7x0.9	-	90.000	PLATED	8
				TOTAL HOLES:	1960

PCB Fabrication Notes:

1. Construction: 8-Layer Rigid PCB
2. For stackup see --------->
3. PCB to be fabricated to IPC-6013 Class II, plate PTH to Class III
4. Inner layers are to be 0.5 oz copper
5. Outer layers are to be 1.0 oz finished copper
6. Board thickness to be 1.5mm +/- 10%
7. Achieve 90 Ohm differential impedance for pairs on layers Top, Inner-1 and Inner_3
   Inner-1 and Inner_3
8. RoHS complaint dialectric to be used
9. The board should be routed along the right and left sides
   and use 'mouse bites' breakaway tabs along the top/bottom sides
10. Green LPI solder mask per IPC-SM-840 Class H
11. White epoxy silk screen
12. Electrical test per IPC-9252 Class 2, 100% coverage
13. Perform DFM check and advise designer of problems

Stackup